

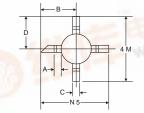
CASCADABLE BROADBAND GaAs MMIC AMPLIFIER DC TO 10GHz

Typical Applications

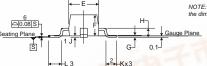
- Narrow and Broadband Commercial and Military Radio Designs
- Linear and Saturated Amplifiers
- Gain Stage or Driver Amplifiers for MWRadio/Optical Designs (PTP/PMP/ LMDS/UNII/VSAT/WLAN/Cellular/DWDM)

Product Description

The NLB-310 cascadable broadband InGaP/GaAs MMIC amplifier is a low-cost, high-performance solution for general purpose RF and microwave amplification needs. This 50Ω gain block is based on a reliable HBT proprietary MMIC design, providing unsurpassed performance for small-signal applications. Designed with an external bias resistor, the NLB-310 provides flexibility and stability. The NLB-310 is packaged in a low-cost, surface-mount plastic package, providing ease of assembly for high-volume tape-and-reel requirements.



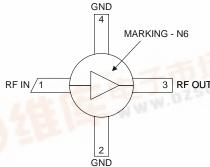
	Symbol	MILLIMETERS			INCHES			
		Min.	Nom.	Max.	Min.	Nom.	Max.	
	Α	0.535 REF.			0.021 REF.			
	В	2.39	2.54	2.69	0.094	0.100	0.106	
	С	0.436	0.510	0.586	0.017	0.020	0.023	
	D	2.19	2.34	2.49	0.086	0.092	0.098	
	Ε	1.91	2.16	2.41	0.075	0.085	0.095	
	F	1.32	1.52	1.72	0.052	0.060	0.068	
	G	0.10	0.15	0.20	0.004	0.006	0.008	
	Н	0.535	0.660	0.785	0.021	0.026	0.031	
1	J	0.05	0.10	0.15	0.002	0.004	0.006	
2	K	0.65	0.75	0.85	0.025	0.029	0.033	
3	L	0.85	0.95	1.05	0.033	0.037	0.041	
4	М	4.53	4.68	4.83	0.178	0.184	0.190	
5	N	4.73	4.88	5.03	0.186	0.192	0.198	



NOTE: All dimensions are in millimeters, and the dimensions in inches are for reference only

Optimum Technology Matching® Applied

☐ Si BJT	GaAs HBT	GaAs MESFET
Si Bi-CMOS	SiGe HBT	☐ Si CMOS
▼ InGaP/HBT	GaN HEMT	☐ SiGe Bi-CMOS



3 RF OUT GND

Package Style: Micro-X, 4-Pin, Plastic

Features

- Reliable, Low-Cost HBT Design
- 12.7dB Gain, +12.6dBm P1dB@2GHz
- High P1dB of +14.9dBm @ 6.0GHz and
 - +13.1dBm@10.0GHz
- Single Power Supply Operation
- 50Ω I/O Matched for High Freq. Use

Ordering Information

NLB-310 Cascadable Broadband GaAs MMIC Amplifier DC to 10GHz

NLB-310-T1 or -T3Tape & Reel, 1000 or 3000 Pieces (respectively)

NLB-310-E Fully Assembled Evaluation Board

Extended Frequency InGaP Amp Designer's Tool Kit nc. Tel (336) 664 1233 NBB-X-K1 RF Micro Devices, Inc.

7628 Thorndike Road Fax (336) 664 0454 Greensboro, NC 27409, USA http://www.rfmd.com

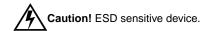
Functional Block Diagram

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Absolute Maximum Ratings

Parameter	Rating	Unit
RF Input Power	+20	dBm
Power Dissipation	300	mW
Device Current	70	mA
Channel Temperature	200	°C
Operating Temperature	-45 to +85	°C
Storage Temperature	-65 to +150	°C

Exceeding any one or a combination of these limits may cause permanent damage.



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Parameter	Specification			Unit	Condition	
Parameter	Min. Typ.		Max.	Onit	Condition	
Overall					V_D =+4.6V, I_{CC} =50mA, Z_0 =50 Ω , T_A =+25°C	
Small Signal Power Gain, S21	12.0	12.7		dB	f=0.1 GHz to 1.0 GHz	
_		10.7		dB	f=1.0GHz to 4.0GHz	
		10.0		dB	f=4.0GHz to 6.0GHz	
	8.5	9.7		dB	f=6.0GHz to 10.0GHz	
		9.6		dB	f=10.0GHz to 12.0GHz	
Gain Flatness, GF		±0.3		dB	f=5.0GHz to 10.0GHz	
Input VSWR		1.6:1			f=0.1 GHz to 4.0 GHz	
		1.75:1			f=4.0GHz to 7.0GHz	
		1.6:1			f=7.0GHz to 11.0GHz	
Output VSWR		1.5:1			f=0.1 GHz to 4.0 GHz	
		1.8:1			f=4.0GHz to 7.0GHz	
		1.6:1			f=7.0GHz to 11.0GHz	
Output Power @						
-1dB Compression, P1dB		12.6		dBm	f=2.0GHz	
		14.9		dBm	f=6.0GHz	
		13.1		dBm	f=10.0GHz	
Noise Figure, NF		5.0		dB	f=3.0GHz	
Third Order Intercept, IP3		+28.9		dBm	f=2.0GHz	
		+27.9			f=6.0GHz	
Reverse Isolation, S12		-17		dB	f=0.1 GHz to 20.0 GHz	
Device Voltage, V _D	4.4	4.6	4.8	V		
Gain Temperature Coefficient, $\delta G_T/\delta T$		-0.0015		dB/°C		
MTTF versus Temperature						
@ I _{CC} =50mA						
Case Temperature		85		°C		
Junction Temperature		125		°C		
MTTF		>1,000,000		hours		
Thermal Resistance						
θις		174		°C/W	$\frac{J_T - T_{CASE}}{V_D \cdot I_{CC}} = \theta_{JC}(^{\circ}C/Watt)$	

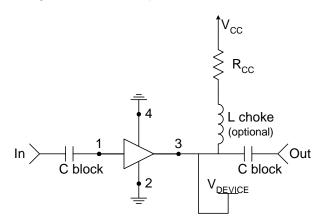
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Pin	Function Description		Interface Schematic
1	RF IN	RF input pin. This pin is NOT internally DC blocked. A DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. DC coupling of the input is not allowed, because this will override the internal feedback loop and cause temperature instability.	
2	GND	Ground connection. For best performance, keep traces physically short and connect immediately to ground plane.	
3	RF OUT	RF output and bias pin. Biasing is accomplished with an external series resistor and choke inductor to V_{CC} . The resistor is selected to set the DC current into this pin to a desired level. The resistor value is determined by the following equation: $R = \frac{(V_{CC} - V_{DEVICE})}{I_{CC}}$ Care should also be taken in the resistor selection to ensure that the current into the part never exceeds maximum datasheet operating current over the planned operating temperature. This means that a resistor between the supply and this pin is always required, even if a supply near 5.0V is available, to provide DC feedback to prevent thermal runaway. Because DC is present on this pin, a DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. The supply side of the bias network should also be well bypassed.	RF IN O
4	GND	Same as pin 2.	

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Typical Bias Configuration

Application notes related to biasing circuit, device footprint, and thermal considerations are available on request.



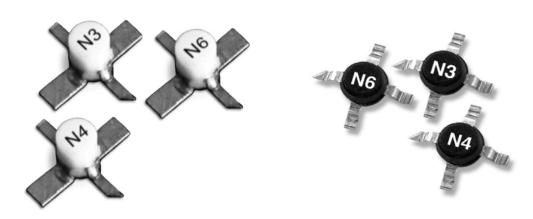
Recommended Bias					
Supply Voltage, V _{CC} (V)	8	10	12	15	20
Bias Resistor, $R_{CC}(\Omega)$	60	100	140	200	300

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Extended Frequency InGaP Amplifier Designer's Tool Kit NBB-X-K1

This tool kit was created to assist in the design-in of the RFMD NBB- and NLB-series InGap HBT gain block amplifiers. Each tool kit contains the following.

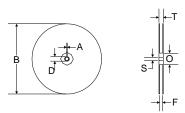
- 5 each NBB-300, NBB-310 and NBB-400 Ceramic Micro-X Amplifiers
- 5 each NLB-300, NLB-310 and NLB-400 Plastic Micro-X Amplifiers
- 2 Broadband Evaluation Boards and High Frequency SMA Connectors
- Broadband Bias Instructions and Specification Summary Index for ease of operation



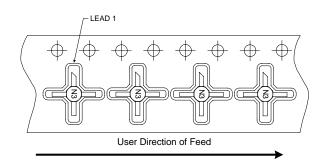
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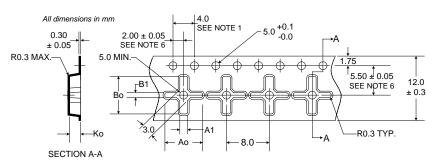
Tape and Reel Dimensions

All Dimensions in Millimeters



	14.732 mm (7") REEL	Plastic, Micro-X		
	ITEMS	SYMBOL	SIZE (mm)	SIZE (inches)
	Diameter	В	178 +0.25/-4.0	7.0 +0.079/-0.158
FLANGE	Thickness	Т	18.4 MAX	0.724 MAX
	Space Between Flange	F	12.8 +2.0	0.50 +0.08
	Outer Diameter	0	76.2 REF	3.0 REF
HUB	Spindle Hole Diameter	S	13.716 +0.5/-0.2	0.540 +0.020/-0.008
пов	Key Slit Width	Α	1.5 MIN	0.059 MIN
	Key Slit Diameter	D	20.2 MIN	0.795 MIN



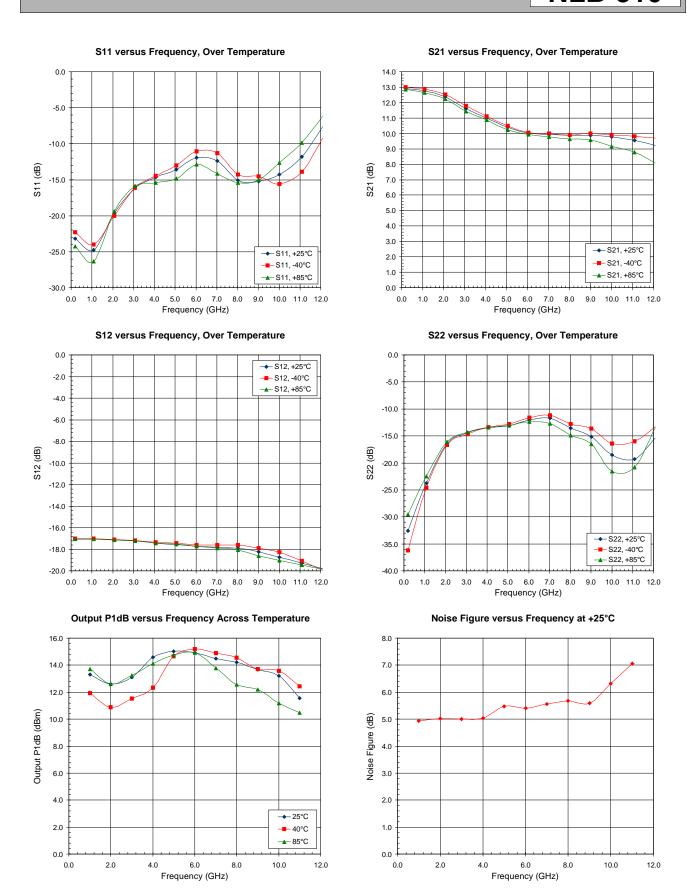


NOTES:

- 1. 10 sprocket hole pitch cumulative tolerance ±0.2.

- 2. Camber not to exceed 1 mm in 100 mm.
 3. Material: PS+C.
 4. Ao and Bo measured on a plane 0.3 mm above the bottom of the pocket.
- 5. Ko measured from a plane on the inside bottom of the pocket to the surface of the carrier.6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.
- Ao = 7.0 MM
- A1 = 1.8 MM
- Bo = 7.0 MM
- B1 = 1.3 MM
- Ko = 2.1 MM

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Note: The s-parameter gain results shown include device performance as well as evaluation board and connector loss variations. The insertion losses of the evaluation board and connectors are as follows:

1 GHz to 4 GHz=-0.06 dB 5 GHz to 9 GHz=-0.22 dB 10 GHz to 14 GHz=-0.50 dB 15 GHz to 20 GHz=-1.08 dB

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